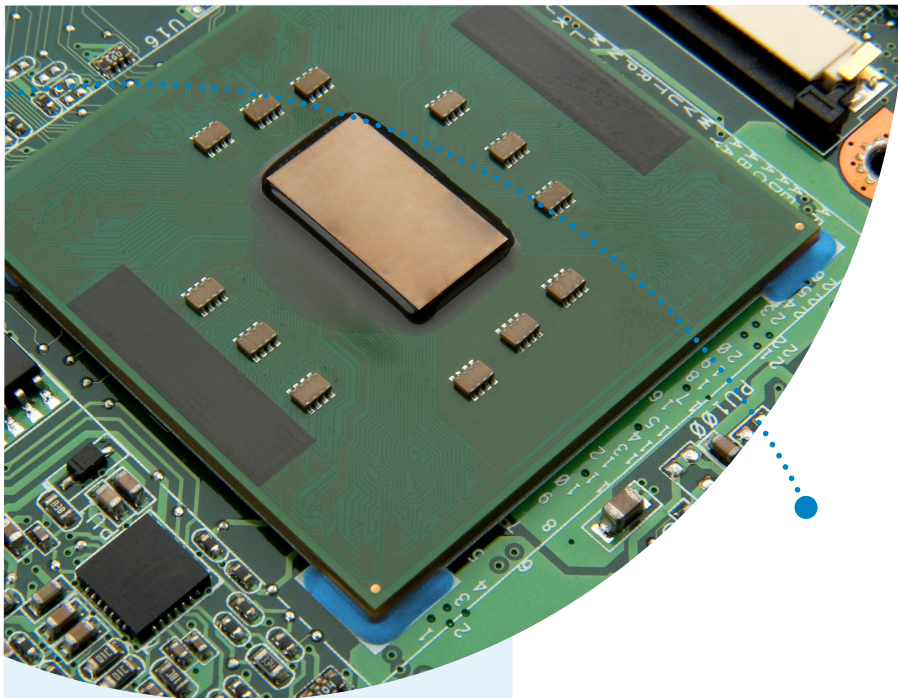


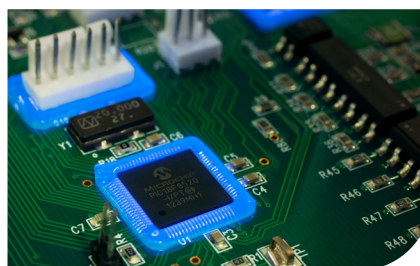


- Fast, ambient dispense and cure in seconds
- Engineered bead shape for wetting both board surface and component edge without seeping into shadowed area
- Highly thixotropic for zero movement prior to cure
- Low modulus for minimal stress in component interfaces
- Exhibit improved bond strength for die and pry testing
- Halogen and silicone free
- RoHS Compliant
- Easy rework – adhesive leaves no residue on solder pads or between solder balls
- Materials enhance PCB life and reduce stress on interconnects during push, pull, shock, drop, and vibration
- Eliminate leadless component (BGA/VGA) interconnect cracking due to CTE mismatch
- Post reflow application
- Simple visual inspection
- Very low VOCs
- No solvents added
- No energy required for curing ovens

Ruggedizing Adhesives for Electronic Components

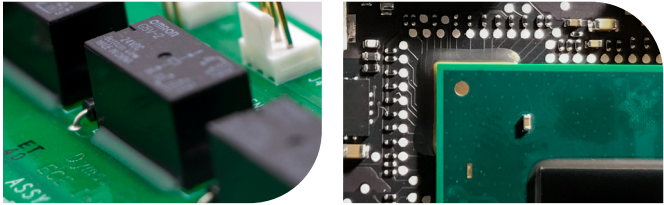
Ensuring the reliability of critical components on printed circuit boards (PCBs) is essential throughout manufacturing, assembly, qualification, and the full service life of the device. A single failure—such as a compromised ball grid array (BGA) interconnect—can jeopardize the performance of an entire electronic system.

Dymax has developed a portfolio of light-curable adhesives specifically formulated to secure critical PCB components. These adhesives deliver an ideal combination of mechanical strength, environmental resistance, and production efficiency. Designed for fast-paced electronic assembly, Dymax adhesives cure in seconds with light, helping manufacturers enhance product durability without sacrificing throughput.



Available Adhesives

Dymax light-curable ruggedizing adhesives provide fast, reliable reinforcement for PCB components. Ideal for component ruggedization, staking, and reinforcement against shock, vibration, and other stresses. Materials suitable for fine-pitch, leadless devices, and as an underfill alternative are available.



Product	Unique Features	Viscosity, cP	Durometer	Tensile at Break, MPa [psi]	Elongation, %	Modulus of Elasticity, MPa [psi]	Linear Shrinkage, %
9309-SC	See-Cure: blue-to-colorless upon exposure to UV/Visible light	45,000	D57	22 [3,200]	140	163 [23,800]	1.2
9310	Secondary heat cure for shadow areas	51,000	D60	12 [1,700]	145.5	103 [15,000]	2.1
9422-SC	See-Cure (blue-to-colorless upon exposure to UV/Visible light)	38,000	D50	16 [2,300]	170	98 [14,000]	1.6
9773	Low outgassing (ASTM E595); Low ionic content (Mil-Std 883 Method 5011); NASA MAPTIS listed (Material Code 09907)	54,00	D47	12 [1,700]	85	103 [15,000]	0.6

See-Cure Technology

Dymax adhesives formulated with See-Cure technology have built-in cure validation that makes it easy for operators or simple automated inspection equipment to confirm cure without investing in additional specialized equipment. These materials are bright blue in their uncured state, making them highly visible when dispensed onto substrates. Workers can easily confirm the adhesive placement and quantity with just their eyes. After the adhesive is exposed to light, the color transitions from blue to colorless. This cure indicator ensures the adhesive is completely cured, providing a critical safety feature for manufacturing processes.

